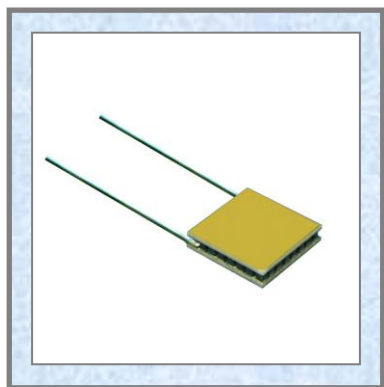
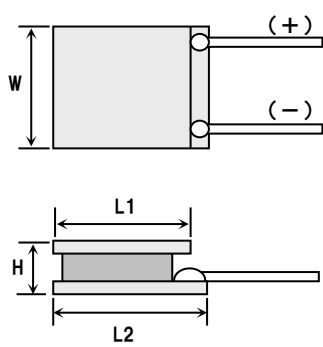


THERMO MODULE DATA

Model **KSEH031** RoHS 2002/95/EC Compliant



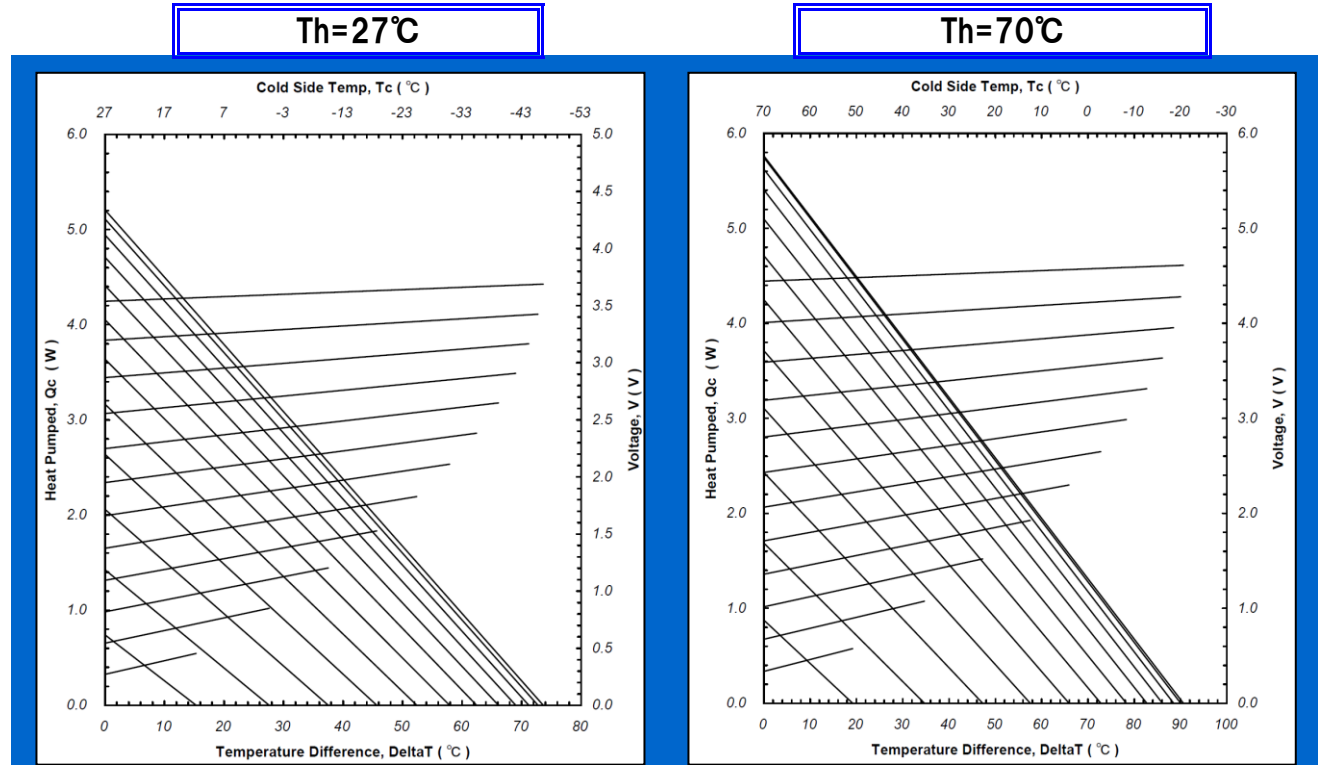
Th	$\Delta T_{max}(^{\circ}C)$	I_{max}(A)	V_{max}(v)	Q_{cmax}(w)
27°C	75	2.4	3.7	5.2
70°C	93	2.4	4.7	5.7
Size(mm)	W	L1	L2	H
Tolerance(mm)	8.0	8.0	8.0	1.65
Metallization	Cu-Ni-Au			
Ceramic material	Alumina			
Assembly solder	SnSb (melting point:232°C)			



Option

Assembly solder	AuSn (melting point:280°C)
Ceramic material	All models can be assembled with alumina &/or aluminum nitride ceramics.
Pretinning solder	InSn (melting point:117°C), BiSn (melting point:138°C), SnAgCu (melting point:217°C) is also available, when AuSn is selected for assembly solder.

Performance Diagram



Ambient	Nitrogen
Current value	I = 0.2 – 2.4 A (Step = 0.20 A)

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